

AMENDMENTS TO THE SPECIFICATION

Please replace paragraph [0037] with the following:

FIG. 4 illustrates a process for chucking and dechucking a substrate in accordance with an embodiment of the present invention. A substrate confinement apparatus is provided having at least one substrate retainer in accordance with an embodiment of the present invention (100). A ~~Substrate~~substrate may be positioned in the substrate confinement apparatus for processing (110). This can be done in a number of ways, including but not limited to an end-effector bringing the substrate to the confinement apparatus. An actuator may be used to urge ~~the flexure and retainer body~~one of the substrate retainers toward the substrate, and thereby urge a contact surface of one of the retainer ~~body~~bodies into contact with the substrate back side (120). ~~The One of the~~ retainer ~~body~~bodies may be coupled to the substrate back side (130). This coupling may be through number of coupling forces, such as vacuum/suction applied through the actuator. The actuator may be retracted from ~~the flexure and~~ substrate retainer, thereby leaving the retainer body coupled to the substrate back side and allow substrate and substrate retainer to settle into a neutral state (140). The global confinement system may be activated to maintain the substrate in a substantially planar position (150). In one embodiment the global confinement system may include a plurality of alternating air jets and vacuum ports. Once confined in plane and restricted from lateral in plane movement, the substrate is ready for processing. To de-chuck the wafer, a reverse of the above process may be used.